

ISSP2011 EXHIBIT

ISSP2011 Committee,
The Vacuum Society of Japan

The ISSP Panel Exhibit*¹ will be held in conjunction with The 11th International Symposium on Sputtering and Plasma Processes (ISSP2011) at the Kyoto Research Park from July 6 to 8, 2011. It will feature the broad spectrum of equipment, instruments, materials, systems, services, etc. for sputtering and plasma processes. At the last Exhibit, ISSP2009, 15 companies exhibited their offerings, and exchanged the information with about 300 attendees. This is the best opportunity for you to present, face-to-face, your products and services to a vital market. The Panel Exhibit will be opened parallel to ISSP2011 poster presentation at the same room. The ISSP2011 committee requests your company to attend this exhibition as an exhibitor. The up-to-date information can be seen at our web site: <http://issp2011.org/>. Please don't miss the terrific opportunity!

Your presentation at the technical session of the symposium is strongly recommended as well as the panel exhibit, which is expected to dramatically improve the impact of your company. (In this case, please apply as a normal presenting author.)

Exhibit Details

[Scope]

Process equipment (sputtering, evaporation, MBE, CVD, etching, etc.)
Analyzer, controller, and measurement apparatus
Related materials and components (Sputtering target, etc.)

[Location and term]

Kyoto Research Park, Kyoto, Japan
Exhibit: From 17:00 July 6 to 17:00 July 8, 2011 (Symposium: From 10:00 July 6 to 17:00 July 8)
(Closing time is tentative.)

[Exhibit fee]

¥ 120,000/unit (Japanese yen)
(Including the exhibit fee ¥100,000 and the registration fee ¥20,000)

[Special favor]

- *The exhibitor can show one-page, monochrome, and camera-ready advertisement on the proceedings for free. Please tolerate that the printing quality is not so high grade.
- *We prepare a link to your home site on our web page, <http://issp2011.org/>, according to your request.
- *In accordance with the request of exhibitor, an automatic CM slide presentation by Powerpoint (without sound, 30sec/company, no page limit) will be available during the break time of oral session. (Details will be informed later.)

[How to apply]

Please fill the application form (the last page) and send it to exhibit@issp2011.org by email.
Please attach the banner image file of your company, if you wish to make link point of your company's home page on the ISSP2011 web site.

Deadline: May 16, 2011

If you want to apply the one-page advertisement on the proceedings, please send a PDF file or a paper-printed copy to the committee office (see the end of this article).

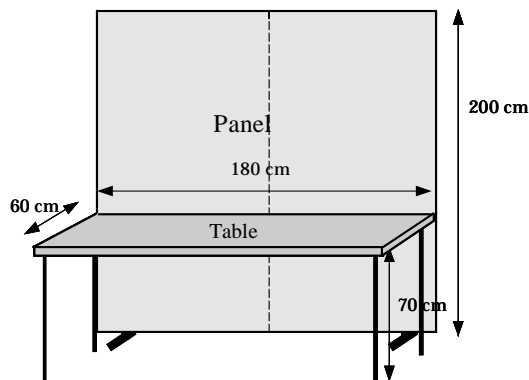
*¹ Notice: ISSP2011 Exhibit is NOT the Manufacturer's Presentation which will be included in the technical program.

[Policy]

- *Description language is English.
- *At least one person is required to explain the panels. He/she is entitled to attend all the session of ISSP2011 for free.
- *For extra two persons of exhibitor, the registration fee is ¥20,000 per person. From the 4th person and up, please register as a normal participant.
- *The carriage of all the exhibiting materials is to be made by yourself.
- *Don't remove the panel before the closing of ISSP2011.

[Configuration]

- *One unit of exhibition space consists of a panel of about 180 cm (width) × 200 cm (height). and a desk of 180 cm (width) × 60 cm (depth) × 70 cm (height).
- *The total weight of exhibiting materials on the desk should be less than 10 kg.
- *If you need more space, you may use multiple exhibition units by paying additional fee. The acceptance will be informed later.
- *Utilities of electrical power are available for personal computer use. It, however, is limited to 2 A (AC100 V).
- *If you would like to make any special exhibition, please consult with us.



[Questions and Application]

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Exhibitors of the Past ISSP Exhibit

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| <ul style="list-style-type: none">• Advanced Energy Japan• AIMEC Corp.• ASTECH Corp.• BOC Coating Technology• Canon ANELVA Corp.• ENI JAPAN Ltd.• Fraunhofer-Institut für Elektronenstrahl- und Plasmatechnik• FTS Corp.• Fujikin Inc.• Gencoa Ltd.• Hakuto Co., Ltd.• HITACHI ZOSSEN Corp.• Hüttinger Elektronik GmbH• JAPAN ENERGY Corp.• JEOL Ltd.• Kurt J. Lesker Company• Landmark Technology Corp.• MAKPLE Co. Ltd• MARUBUN Corp.• Matsubo Co., Ltd.• MITSUBISHI MATERIALS Corp.• Oerlikon Japan Co., Ltd.• Oerlikon Leybold Vacuum Japan Co., Ltd. | <ul style="list-style-type: none">• NANO SCIENCE CORPORATION• NANOMETRICS JAPAN• NIHON VEECO K. K.• NIPPON MINING & METALS CO., LTD.• NOA SYSTEMS Inc.• NTT AFTY Corp.• OXFORD INSTRUMENTS• PEGASUS Software Inc.• SAES GETTERS JAPAN Co., Ltd.• Sanyu Electron Co., Ltd.• Science Technology Co., Ltd.• SHINCRON Co., Ltd.• SHOWA SHINKU Co., Ltd.• Singulus Technologies AG• Sputtered Films, Inc.• TDY INC.• THERMO RIKO CO., LTD.• ULVAC CRYOGENICS INC.• ULVAC JAPAN, Ltd.• ULVAC-PHI, INC.• UNIVERSAL SYSTEMS Co., Ltd.• VACUUM METALLURGICAL Co., Ltd.• VIC International Co., Ltd.• Von Ardenne Anlagentechnik GmbH |
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